

Thermal paste

Paste 8702 (ex PA 20)

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- **silicone- and solvent-free heat-conducting paste**
 - **1 component**
 - **CMR-free ***
 - **high-performance and electrically insulating**
 - **excellent thermal conductivity**
 - **no metallic fillers**
 - **high-long-term stability**
 - **good creeping properties**
 - **ideal for different cooling applications, improves the heat-transfer**

* not subject to CMR labelling according to section 2 of the safety data sheet

Product specification:

Type:	Non-curing and non-drying paste	
Viscosity (23 °C):	Paste 8702	150'000 – 200'000 mPa·s
Density (22 °C):	Paste 8702	2.20 – 2.50 g/cm ³
Colour:	Nature (cream)	
Shelf life:	6 months in sealed original containers when stored in dry conditions (15°C to 25°C).	

Physical properties:

Thermal conductivity:	2.0 – 2.3 W/(m·K) (22 °C) 2.0 – 2.3 W/(m·K) (60 °C optional)	DIN EN ISO 22007
Thermal resistance:	No blooming after 4 h at 200 °C	
Operating temperature:	-60 °C up to +200 °C	

Electrical properties:

Dielectric strength:	25 kV/mm	IEC 60243-1, VDE 0303, TI.2
Volume resistance:	$10^{16} \Omega \cdot \text{cm}$ (23 °C/ 50 % r.F.)	IEC 60243-1, VDE0303, TI.30

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